

Thermal Management

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Typical Properties	HTC	HTCX	HTCP	HTCPX	HTS	HTSP	TCOR	TCER	TBS	ER2074
Base Material	Non-Silicone Oil	Non-Silicone Oil	Non-Silicone Oil	Non-Silicone Oil	Silicone Oil	Silicone Oil	Silicone RTV	Silicone RTV	Epoxy	Epoxy
Thermal Conductivity (W/mK)	0.9	1.35	2.5	3.4	0.9	3	1.8	2.2	1.1	1.26
Density (g/ml)	2.04	2.61	3	3.1	2.1	3	2.3	2.3	2.8	2.09
Temperature Range (°C)	-50 to +130	-50 to +130	-50 to +130	-50 to +130	-50 to +200	-50 to +200	-50 to +230	-50 to +230	-40 to +120	-40 to +130
Evaporation Weight Loss (96hrs @ 100°C IP-183)	≤1.00%	<0.40%	≤1.00%	≤1.00%	≤0.80%	≤0.80%	N/A	N/A	N/A	N/A
Dielectric Strength (kV/mm)	42	42	42	42	18	18	>8	>8	11	10
Electrical Insulation (Ω/cm)	10 ¹⁴	10 ¹⁴	10 ¹⁴	10 ¹⁴	10 ¹⁵	10 ¹⁵	10 ¹⁴	10 ¹⁴	10 ¹⁴	10 ¹⁵
Cure Time (Hours @ 20°C / Minutes @ 100°C)	N/A	N/A	N/A	N/A	N/A	N/A	24 hours*	24 hours*	48/45	24/60
Viscosity/Pa s	Paste: 205-225	Paste: 127-141	Paste: 101-112	Paste: 606-670	Paste: 201-227	Paste: 42-48	Paste: 140-150	Paste: 80-90	Mixed System Adhesive: 70-80	Mixed System Resin: 167

*Requires moisture to cure, elevated temperatures not recommended unless moisture is present.